

**IN THE CLAIMS:**

1. (Currently Amended) A silicone-based adhesive sheet, comprising a first layer of a curable silicone composition ~~on one side of said sheet~~, and a second layer ~~disposed adjacent to and in contact with said first layer, said second layer comprising~~ [[of]] a slower curing silicone composition than said first layer ~~on the other side of said sheet~~.
2. (Previously Presented) The silicone-based adhesive sheet of Claim 1, wherein either of said curable silicone compositions has a plasticity number of from 100 to 800, as specified by JIS K 6249.
3. (Previously Presented) The silicone-based adhesive sheet of Claim 1, wherein either of said curable silicone compositions is a hydrosilylation-curable silicone composition.
4. (Original) The silicone-based adhesive sheet of Claim 3, wherein either of said hydrosilylation-curable silicone compositions is a curable silicone composition comprising (A) an organopolysiloxane having at least two alkenyl groups per molecule; (B) a filler; (C) an organopolysiloxane having at least two silicon-bonded hydrogen atoms per molecule; (D) an adhesion promoter; and (E) a hydrosilylation catalyst.
5. (Original) The silicone-based adhesive sheet of Claim 1, further comprising a protective film on at least one side of the silicone-based adhesive sheet.
6. (Previously Presented) The silicone-based adhesive sheet of Claim 1, wherein at least one of said first and second layers is cured.
- 7-10. (Cancelled)

11. (Withdrawn-currently amended) A method of bonding a semiconductor chip to a chip attachment component, comprising the steps of:

- (1) producing the semiconductor chip by dicing a laminated body comprising a cured silicone layer bonded to a wafer, a layer of curable silicone composition adjacent and firmly bonded to said cured silicone layer, a protective film firmly bonded to said layer of curable silicone composition, and a sheet adhesively attached to said protective film;
- (2) peeling said protective film and said sheet from said semiconductor chip;
- (3) bonding said semiconductor chip to said chip attachment component by pressing said semiconductor chip to said chip attachment component via said layer of curable silicone composition; and
- (4) curing said layer of curable silicone composition.

12. (Withdrawn-currently amended) The method of Claim 11, wherein the cured silicone layer and the layer of curable silicone composition firmly bonded to the cured silicone layer are formed by applying a first layer of a curable silicone composition (I) to the wafer, applying a second layer of a curable silicone composition (II) to the first layer, the second layer endowed with a lower curing rate than the first layer, and curing the first layer, such that the second layer of composition (II) is prevented from being cured.

13. (Withdrawn) The method of Claim 12, wherein either of said curable silicone compositions (I) and (II) has a plasticity number of from 100 to 800, as specified by JIS K 6249.

14. (Withdrawn) The method of Claim 12, wherein either curable silicone composition (I) or curable silicone composition (II) is a hydrosilylation-curable composition.

15. (Withdrawn) The method of Claim 14, wherein either of said hydrosilylation-curable silicone compositions is a curable silicone composition comprising at least (A) an organopolysiloxane having at least two alkenyl groups per molecule; (B) a filler; (C) an organopolysiloxane having at least two silicon-bonded hydrogen atoms per molecule; (D) an adhesion promoter; and (E) a hydrosilylation catalyst.

16. (Withdrawn-currently amended) A method of fabricating a semiconductor device comprising a semiconductor chip, a silicone-based adhesive sheet, and a semiconductor chip attachment component, wherein the method comprises:

- a) fabricating the silicone-based adhesive sheet having a first layer of curable silicone composition (I) ~~on one side~~ and ~~having~~ a second layer disposed adjacent to and in contact with said first layer, said second layer comprising [[of]] a slower curing curable silicone composition (II) than said first layer of composition (I) ~~on the other side~~, and
- b) curing said first layer of composition (I) so that said second layer of composition (II) remains uncured while said first layer of composition (I) is kept in contact with the semiconductor chip, and said second layer of composition (II) is subsequently cured while kept in contact with the semiconductor chip attachment component.

17. (Withdrawn-currently amended) A method of fabricating a semiconductor device comprising a semiconductor chip, a silicone-based adhesive sheet, and a semiconductor chip attachment component, wherein the method comprises:

- a) fabricating the silicone-based adhesive sheet having a first layer of curable silicone composition (I) ~~on one side~~ and ~~having~~ a second layer disposed adjacent to and in contact with said first layer, said second layer comprising [[of]] a slower curing curable silicone composition (II) than said first layer of composition (I) ~~on the other side~~, and
- b) curing said first layer of composition (I) so that said second layer of composition (II) remains uncured while said first layer of composition (I) is kept in contact with the semiconductor chip attachment component, and said second layer of composition (II) is subsequently cured while kept in contact with the semiconductor chip.

18. (Withdrawn) The method of Claim 17, wherein either of said curable silicone compositions has a plasticity number of from 100 to 800, as specified by JIS K 6249.

19. (Withdrawn) The method of Claim 17, wherein either of said curable silicone compositions is a hydrosilylation-curable composition.

20. (Withdrawn) The method of Claim 19, wherein said hydrosilylation-curable silicone composition comprises at least (A) an organopolysiloxane having at least two alkenyl groups per molecule; (B) a filler; (C) an organopolysiloxane having at least two silicon-bonded hydrogen atoms per molecule; (D) an adhesion promoter; and (E) a hydrosilylation catalyst.

21. (Withdrawn-currently amended) A method of fabricating a semiconductor device comprising a semiconductor chip, a silicone-based adhesive sheet, and a semiconductor chip attachment component, wherein the silicone-based adhesive sheet comprises a cured silicone layer ~~on one side~~ and a layer of curable silicone composition disposed adjacent to and in contact with said cured silicone layer ~~on the other side~~; wherein the method comprises:

- a) bonding said cured silicone layer so that the layer of curable silicone composition remains uncured while said cured silicone layer is kept in contact with a semiconductor chip, and subsequently
- b) curing said layer of curable silicone composition while said layer of curable silicone composition is kept in contact with a semiconductor chip attachment component.

22. (Withdrawn-currently amended) A method of fabricating a semiconductor device comprising a semiconductor chip, a silicone-based adhesive sheet, and a semiconductor chip attachment component, wherein the silicone-based adhesive sheet comprises a cured silicone layer ~~on one side~~ and a layer of curable silicone composition disposed adjacent to and in contact with said cured silicone layer ~~on the other side~~; wherein the method comprises:

- a) bonding said cured silicone layer so that the layer of curable silicone composition remains uncured while said cured silicone layer is kept in contact with the semiconductor chip attachment component, and subsequently
- b) curing said layer of curable silicone composition while said layer of curable silicone composition is kept in contact with said semiconductor chip.

23. (Withdrawn) The method of Claim 22, wherein said curable silicone composition has a plasticity number of from 100 to 800, as specified by JIS K 6249.

24. (Withdrawn) The method of Claim 22, wherein said curable silicone composition is a hydrosilylation-curable composition.

25. (Withdrawn) The method of claim 24, wherein said hydrosilylation-curable silicone composition comprises (A) an organopolysiloxane having at least two alkenyl groups per molecule; (B) a filler; (C) an organopolysiloxane having at least two silicon-bonded hydrogen atoms per molecule; (D) an adhesion promoter; and (E) a hydrosilylation catalyst.

26. (Withdrawn) A semiconductor device prepared by the method of Claim 11.

27. (Withdrawn) The method of Claim 16, wherein either of said curable silicone compositions has a plasticity number of from 100 to 800, as specified by JIS K 6249.

28. (Withdrawn) The method of Claim 16, wherein either of said curable silicone compositions is a hydrosilylation-curable composition.

29. (Withdrawn) The method of Claim 21, wherein said curable silicone composition has a plasticity number of from 100 to 800, as specified by JIS K 6249.

30. (Withdrawn) The method of Claim 21, wherein said curable silicone composition is a hydrosilylation-curable composition.

31. (Withdrawn) A semiconductor device prepared by the method of Claim 16.

32. (Withdrawn) A semiconductor device prepared by the method of Claim 17.

33. (Withdrawn) A semiconductor device prepared by the method of Claim 21.

34. (Withdrawn) A semiconductor device prepared by the method of Claim 22.

35. (New) A silicone-based adhesive sheet of Claim 1, wherein said slower curing silicone composition of said second layer has a curing time at least five times greater than said curable silicone composition of said first layer based on the 90% vulcanizing times of said first and second layers at 130°C as specified by JIS K 6300.